

MOSFET - Power, Single N-Channel, TOLL 100 V, 1.5 mΩ, 300 A

NVBLS1D5N10MC

Features

- Low R_{DS(on)} to Minimize Conduction Losses
- Low Q_G and Capacitance to Minimize Driver Losses
- AEC-Q101 Qualified and PPAP Capable
- Lowers Switching Noise/EMI
- These Devices are Pb-Free and are RoHS Compliant

MAXIMUM RATINGS ($T_J = 25^{\circ}C$ unless otherwise noted)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	100	V
Gate-to-Source Voltage	Э		V_{GS}	±20	V
Continuous Drain		T _C = 25°C	I _D	300	Α
Current R _{θJC} (Notes 1, 3)	Steady	T _C = 100°C		214	
Power Dissipation	State	T _C = 25°C	P_{D}	331	W
R _{θJC} (Note 1)		T _C = 100°C		165	
Continuous Drain		T _A = 25°C		35.5	Α
Current R _{θJA} (Notes 1, 2, 3)	Steady	T _A = 100°C		25.1	
Power Dissipation	State	T _A = 25°C	P_{D}	4.5	W
R _{θJA} (Notes 1, 2)		T _A = 100°C		2.3	
Pulsed Drain Current	$T_A = 25^{\circ}C, t_p = 10 \mu s$		I _{DM}	900	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	-55 to +175	°C
Source Current (Body Diode)			I _S	255	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{L(pk)} = 27.1 A)			E _{AS}	1652	mJ
Lead Temperature for Soldering Purposes (1/8" from case for 10 s)			TL	260	°C

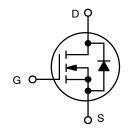
Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL RESISTANCE MAXIMUM RATINGS

Parameter	Symbol	Value	Unit
Junction-to-Case - Steady State	$R_{\theta JC}$	0.45	°C/W
Junction-to-Ambient - Steady State (Note 2)	$R_{\theta JA}$	33	

- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.
- 2. Surface-mounted on FR4 board using a 650 mm², 2 oz. Cu pad.
- Maximum current for pulses as long as 1 second is higher but is dependent on pulse duration and duty cycle.

V _{(BR)DSS}	R _{DS(ON)} MAX	I _D MAX
100 V	1.5 m Ω @ 10 V	300 A



N-CHANNEL MOSFET



H-PSOF8L CASE 100CU

MARKING DIAGRAM



A = Assembly Location
Y = Year
WW = Work Week
ZZ = Lot Traceability
1D5N10MC = Specific Device Code

ORDERING INFORMATION

See detailed ordering, marking and shipping information in the package dimensions section on page 5 of this data sheet.

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ELECTRICAL CHARACTERISTICS (T_J = 25°C unless otherwise specified)

Parameter	Symbol	Test Condition		Min	Тур	Max	Unit
OFF CHARACTERISTICS					•		•
Drain-to-Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		100			V
Drain-to-Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} /				60		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	$V_{GS} = 0 V,$	T _J = 25°C			10	
		V _{DS} = 100 V	T _J = 125°C			100	μΑ
Gate-to-Source Leakage Current	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS}$; = 20 V			100	nA
ON CHARACTERISTICS (Note 4)							
Gate Threshold Voltage	V _{GS(TH)}	$V_{GS} = V_{DS}, I_D =$: 799 μA	2.0		4.0	V
Threshold Temperature Coefficient	V _{GS(TH)} /T _J				-9.3		mV/°C
Drain-to-Source On Resistance	R _{DS(on)}	V _{GS} = 10 V	I _D = 80 A		1.2	1.5	mΩ
Forward Transconductance	9 _{FS}	V _{DS} = 10 V, I _D	= 80 A		230		S
CHARGES AND CAPACITANCES							
Input Capacitance	C _{ISS}				10100		
Output Capacitance	C _{OSS}	V _{GS} = 0 V, f = 1 MHz	z, V _{DS} = 50 V		5100		pF
Reverse Transfer Capacitance	C _{RSS}				84		1 !
Total Gate Charge	Q _{G(TOT)}				131		
Threshold Gate Charge	Q _{G(TH)}				25		
Gate-to-Source Charge	Q_GS	V _{GS} = 10 V, V _{DS} = 50 V; I _D = 80 A			49		nC
Gate-to-Drain Charge	Q_{GD}				21		
Plateau Voltage	V_{GP}				5		V
SWITCHING CHARACTERISTICS (Note	5)			•			•
Turn-On Delay Time	t _{d(ON)}				39		
Rise Time	t _r	Vcs = 10 V. Vn	s = 50 V.		71		1
Turn-Off Delay Time	t _{d(OFF)}	V_{GS} = 10 V, V_{DS} = 50 V, I_{D} = 80 A, R_{G} = 6 Ω			83		- ns
Fall Time	t _f				90		
DRAIN-SOURCE DIODE CHARACTERIS	STICS			•			•
Forward Diode Voltage	V_{SD}	V _{GS} = 0 V,	T _J = 25°C		0.81	1.3	
		$I_{S} = 80 \text{ A}$ $T_{J} = 125^{\circ}\text{C}$			0.68		V
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, } dI_{S}/dt = 100 \text{ A/}\mu\text{s,}$ $I_{S} = 71 \text{ A}$			110		ns
Reverse Recovery Charge	Q _{RR}				143		nC
Charge Time	ta				49		ns
Discharge Time	t _b				62		ns

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

4. Pulse Test: pulse width $\leq 300~\mu s$, duty cycle $\leq 2\%$.

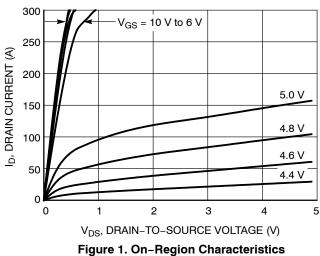
5. Switching characteristics are independent of operating junction temperatures.

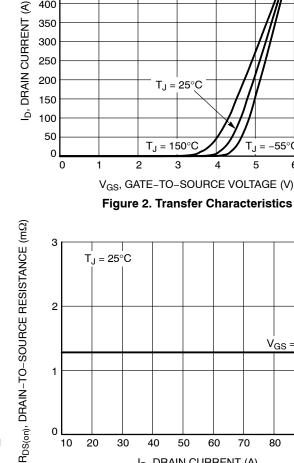
TYPICAL CHARACTERISTICS

500

450

400





V_{DS} = 10 V

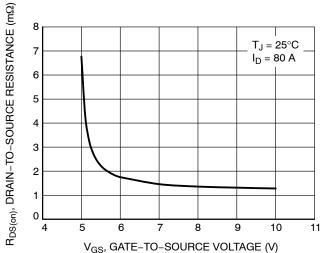
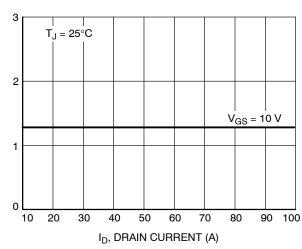


Figure 3. On-Resistance vs. Gate-to-Source Voltage



 $T_{J} = -55^{\circ}C$

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Figure 4. On-Resistance vs. Drain Current and **Gate Voltage**

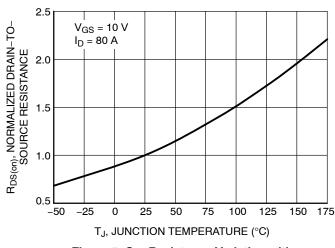


Figure 5. On-Resistance Variation with **Temperature**

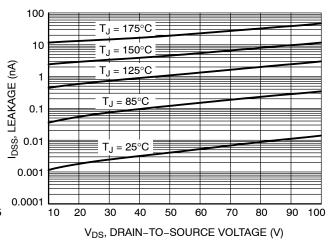


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

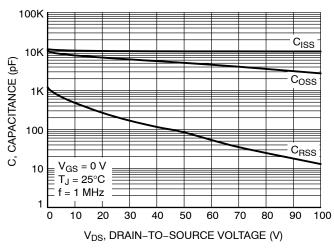


Figure 7. Capacitance Variation

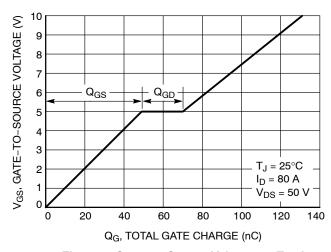


Figure 8. Gate-to-Source Voltage vs. Total Charge

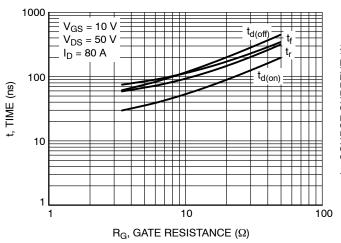


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

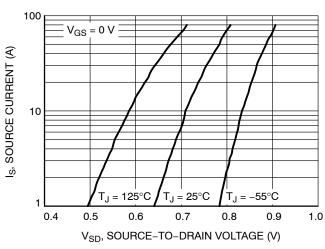


Figure 10. Diode Forward Voltage vs. Current

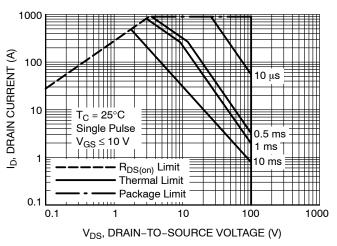


Figure 11. Maximum Rated Forward Biased Safe Operating Area

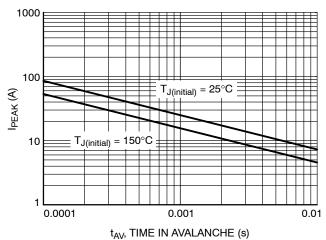


Figure 12. Maximum Drain Current vs. Time in Avalanche

TYPICAL CHARACTERISTICS

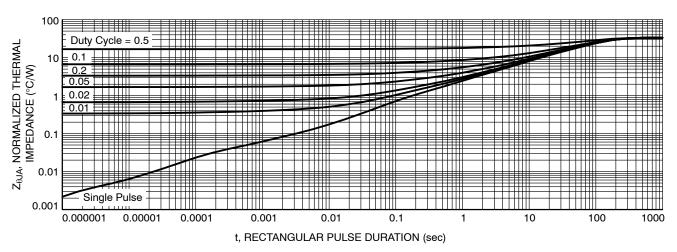


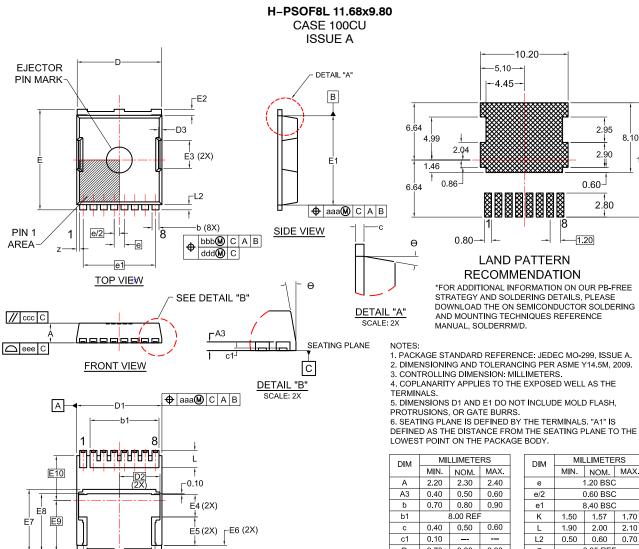
Figure 13. Transient Thermal Impedance

DEVICE ORDERING INFORMATION

Device	Marking	Package	Shipping [†]
NVBLS1D5N10MCTXG	1D5N10MC	H-PSOF8L (Pb-Free)	2000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



|--D5 (3X) D4 -

-D7-**BOTTOM VIEW**

DIM	MILLIMETERS			
	MIN. NOM.		MAX.	
Α	2.20	2.30	2.40	
А3	0.40	0.50	0.60	
b	0.70	0.80	0.90	
b1		8.00 REF	-	
С	0.40	0.50	0.60	
c1	0.10			
D	9.70	9.80	9.90	
D1	9.80	9.90	10.00	
D2		4.73 BSC	;	
D3		0.40 REF		
D4	;	3.75 BSC	;	
D5	_	1.20		
D6	7.40	7.50	7.60	
D7	(8.30)			
E	11.58	11.68	11.78	
E1	10.28	10.38	10.48	
E2	0.60	0.70	0.80	
E3	3.30 REF			
E4	_	2.60		

DIM	MILLIMETERS			
Diivi	MIN. NOM. MAX.			
е	1.20 BSC			
e/2	(0.60 BSC	;	
e1	ũ	3.40 BSC	;	
K	1.50	1.57	1.70	
L	1.90	2.00	2.10	
L2	0.50	0.60	0.70	
Z		0.35 REF		
θ	0°		12°	
aaa	0.20			
bbb	0.25			
ccc	0.20			
ddd	0.20			
eee	0.10			
E5	-	3.30	_	
E6		0.65	_	
E7	7.15 REF			
E8	6.55 6.65 6.75			
E9	5.89 BSC			
E10	5.19 BSC			

2.95

2.90

0.60-2.80 13 28

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